



Material Composition Declaration

EPC2206

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/9/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	25.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	21.8754	87.3895	89.7065	873895
	Silicon oxide	7631-86-9	0.0849	0.3392		3392
	Silicon nitride	12033-89-5	0.0277	0.1106		1106
	Gallium nitride	25617-97-4	0.1031	0.4120		4120
	Aluminum	7429-90-5	0.1682	0.6718		6718
	Aluminum nitride	24304-00-5	0.0249	0.0993		993
	Titanium	7440-32-6	0.0040	0.0160		160
	Titanium nitride	25583-20-4	0.0151	0.0605		605
	Copper	7440-50-8	0.0056	0.0223		223
	Tungsten	7440-33-7	0.0058	0.0230		230
	Polyimide		0.1408	0.5623		5623
Under Bump Metal	Titanium	7440-32-6	0.0037	0.0146	1.2336	146
	Nickel	7440-02-0	0.1086	0.4337		4337
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1966	0.7852		7852
Solder Bump	Tin	7440-31-5	2.2112	8.8334	9.0599	88334
	Silver	7440-22-4	0.0567	0.2265		2265
	Copper	7440-50-8	0.0000	0.0000		0
Sum in total:			25.0321	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.